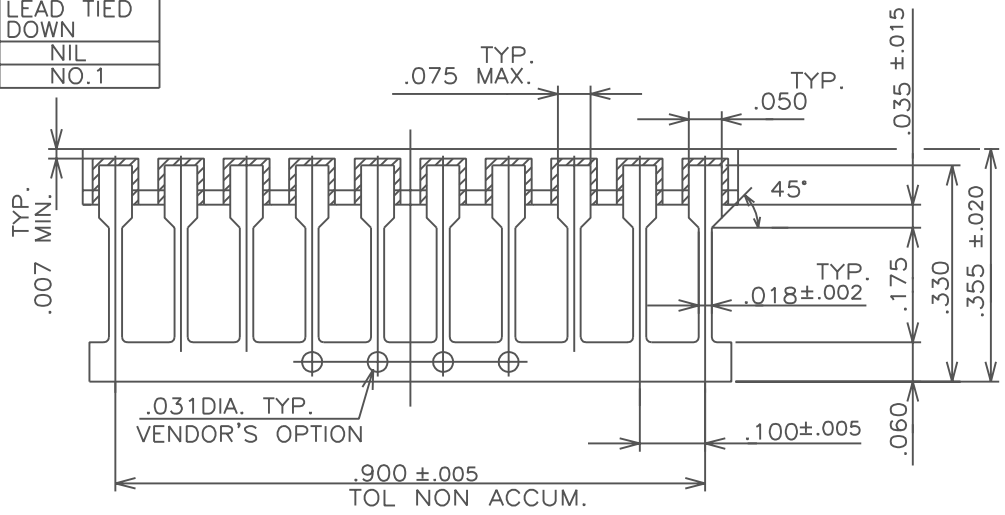


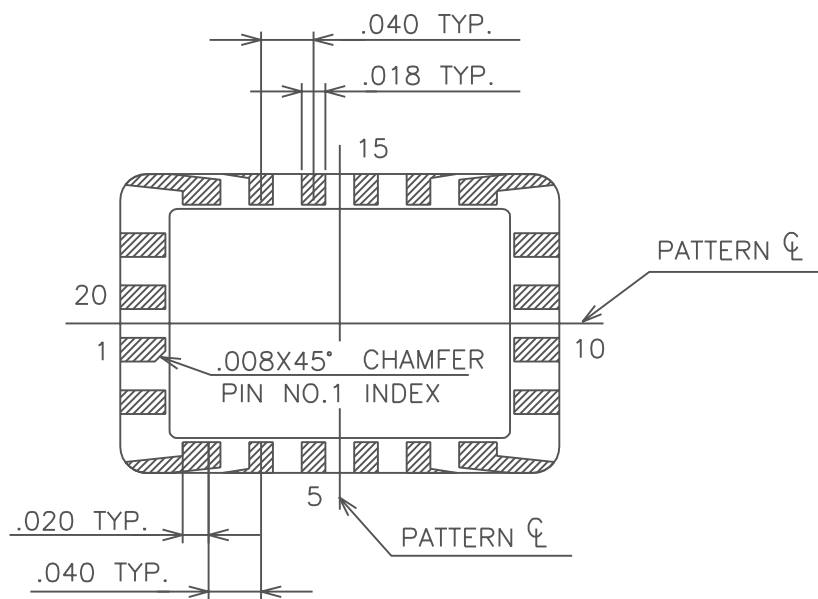
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. LEAD RESISTANCE : 0.3 OHM MAX.

PART NO.	INDEX MARK	LEAD TIED DOWN
-01	●	NIL
-02	⚡	NO.1



SB020G250-2	S=0 D=1
SB020G250-1	S=0 D=0

MODIFICATION	NAME				TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
	20 LEAD SIDE BRAZED PACKAGE								
△ REDRAWN: (CONVERTED CAD DATA) CHANGED	JUN.24.'93	M.S	H.SU S.F	T.A	5/1	AS INDICATED	±.005	T.A	AUG.23.'96
	DATE	DRAWN	CHECKED	APPROVED		KYOCERA	THIRD ANGLE PROJECTION	DRAWING NO.	SHEET
						KYOCERA CORPORATION KYOTO JAPAN		KD-76250-C	1/2



BONDING PATTERN

MODIFICATION						NAME 20 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.S	CHECKED H.SU S.F	APPROVED T.A	DATE AUG.23.'76
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-76250-C	SHEET 2/2			